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IPC-4554

Specification for Immersion Tin Plating for Printed Circuit Boards

IPC-4554
January 2007 A standard developed by IPC

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- Minimize time to market
- Contain simple (simplified) language
- Just include spec information
- Focus on end product performance
- Include a feedback system on use and problems for future improvement

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- Keep people out
- Increase cycle time
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- Contain anything that cannot be defended with data

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Developed by the Plating Processes Subcommitte (4-14) of the Fabrication Processes Committee (4-10) of IPC

Users of this publication are encouraged to participate in the development of future revisions.

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Acknowledgment

Any document involving a complex technology draws material from a vast number of sources. While the principal members of the Plating Processes Subcommittee (4-14) of the Fabrication Processes Committee (4-10) are shown below, it is not possible to include all of those who assisted in the evolution of this standard. To each of them, the members of the IPC extend their gratitude.

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